



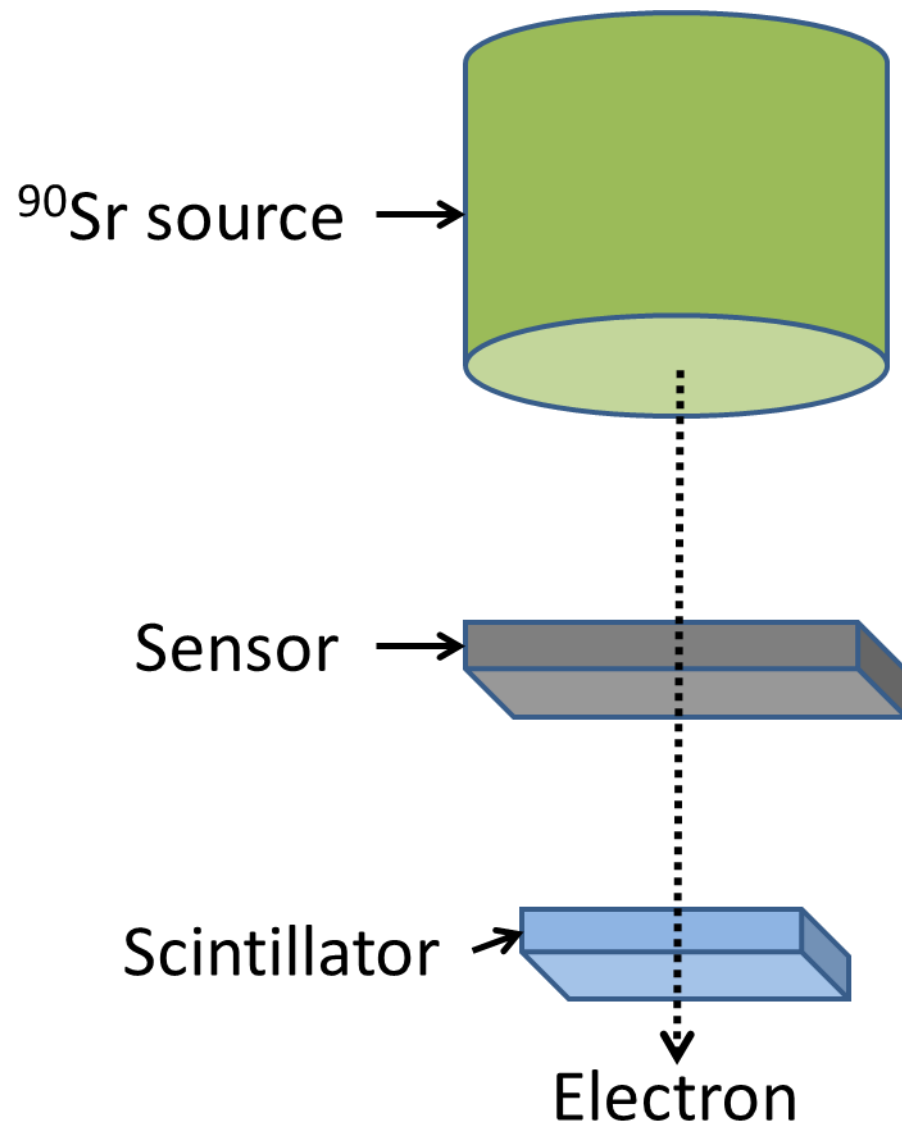
5th Summer School on INtelligent signal processing for FrontiEr Research and Industry

Front End Electronics Lab 3: New Sensors Characterisation - Charge Collection Measurement -



- Give a short introduction into the ALiBaVa system for charge collection measurements
 - Perform some measurements with an un-irradiated silicon strip sensor at different bias voltages
 - Overview of charge collection behaviour of a silicon sensor
 - Analyse data from previous measurements of un-irradiated and irradiated samples
 - Compare the collected charge of irradiated samples with un-irradiated
- In this lab session silicon strip sensors are used to introduce the measurement principle, but the same method can be used for other sensor types for characterization

- ALiBaVa: a joint development of groups in **Liverpool**, **Barcelona** and **Valencia**.
- Uses the beetle ASIC from the LHCb vertex locator
 - Analogue read-out => direct measurement of the collected charge
- Radioactive source (Sr90, beta-source) creates charge carriers in silicon
 - Electrons are minimum ionising particles (MIPs), therefore the expected collected charge in silicon for a fully depleted sensor is well known
- A Scintillator is used for triggering the readout

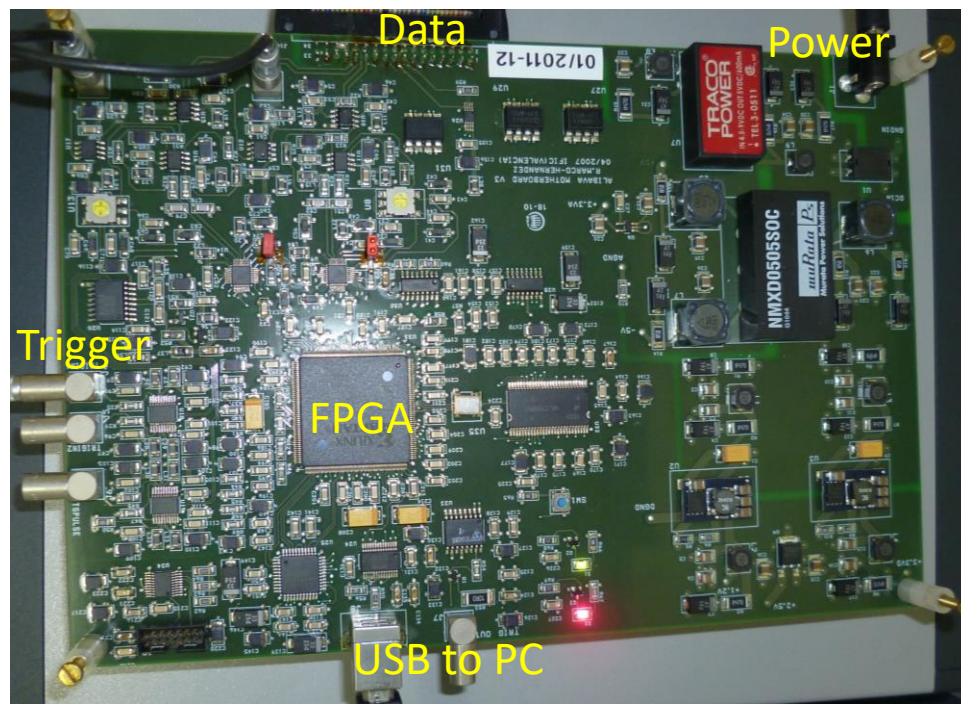
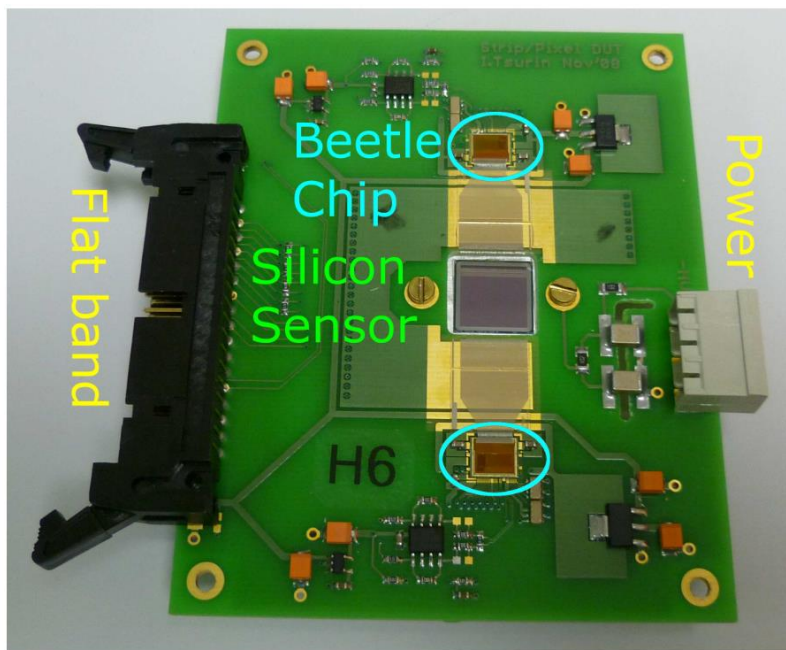


The beetle chip (in this case two) are mounted on a daughterboard, together with the silicon sensor.

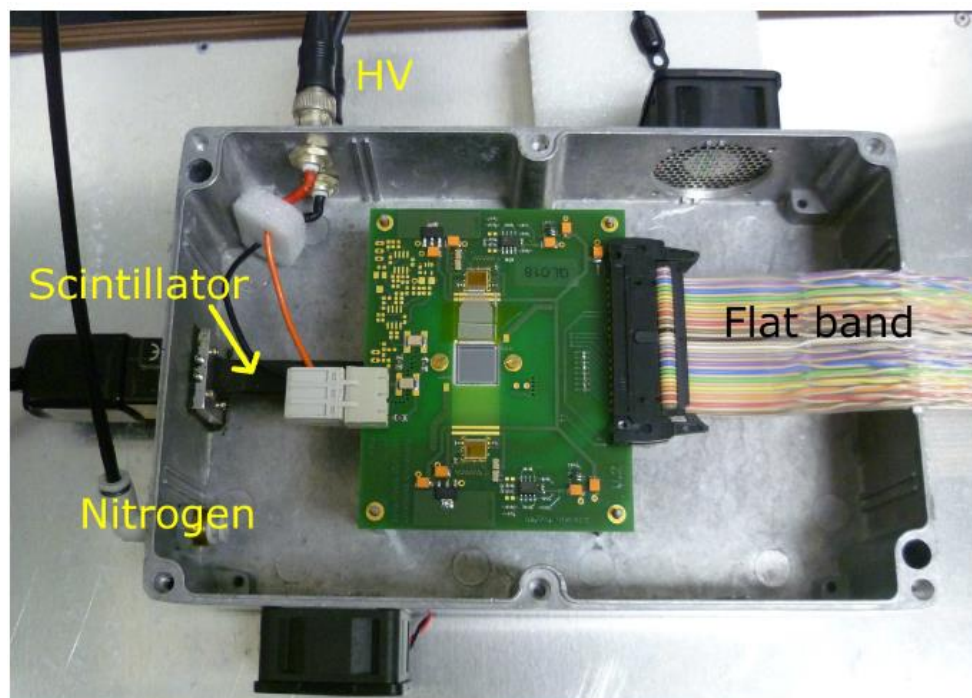
Each front-end channel of one beetle chip is wire-bonded to a strip of the sensor (maximum 128 channels).

In addition the sensor is supplied with high voltage to bias it.

The data is processed/collected by a custom made FPGA board, that sends it to the control PC.



- Daughterboard is mounted in test-box with the scintillator below. A lid with an opening for the source is placed above.
- Usually the system is in a freezer to be able to measure irradiated devices (prevent annealing and reduce high leakage current caused by radiation damage).
- Fans and nitrogen feed improve cooling and prevent condensation.





BACKUP



$$N_{e/h} = \begin{cases} \frac{d}{3.68} \cdot (100.6 + 35.35 \cdot \ln(d)) & \text{for } 13\mu\text{m} < d < 110\mu\text{m} , \\ \frac{d}{3.68} \cdot (190.0 + 16.30 \cdot \ln(d)) & \text{for } 110\mu\text{m} < d < 3000\mu\text{m} , \end{cases}$$

- Number of electron/hole pairs in depleted silicon (MIP) where d is the sensor thickness in μm .



- Pedestal measurement:
 - Random trigger, collect 10000 events
 - Calculates base-line for measurements (middle of ADC range)
 - For each channel individually, gaussian distributed where sigma is associated with the (electronic) noise
 - Calculate common mode noise shift (for each event)
 - Caused by external interference, all channels shift by the same value
- Source measurement:
 - Collect 100000 events, triggered by the scintillator
 - First do pedestal correction and common mode subtraction
 - Time cut reduces number of events to 10% (remove events that are not directly caused by the MIP)
 - Cluster building: pick channel with highest signal and compare against seed cut (signal-to-noise ratio above seed threshold), add all neighbouring channels that are above low-threshold to build full cluster and calculate cluster charge
 - Fill cluster charge in histogram and fit with convoluted Landau-Gauss distribution (energy loss of electrons in matter follows Landau distribution, caused by high energy transfer from delta-electrons).
 - The most probable value (maximum of distribution) corresponds to the collected charge (in ADC units)
- Using the plateau region of a fully depleted un-irradiated sensor (and its known thickness) allows to determine the ADC-to-electron conversion factor